REMARKS

Claims 2 - 16 are pending in the present application. By this Amendment, claims 2 – 16 have been canceled, and new claims 17 - 37 have been added. No new matter has been added. It is respectfully submitted that this Amendment is fully responsive to the Office Action dated February 11, 2004.

Allowable Claim Subject Matter:

Applicants gratefully acknowledge the indication on page 3 of the Office Action that claim 9 would be allowable, if amended to overcome the rejection under 35 U.S.C. §112, second paragraph, as well as to include all of the limitations of the base claim and any intervening claims.

It is respectfully submitted that newly added claim 17 corresponds to canceled claim 9, which is rewritten to overcome the rejection under 35 U.S.C. §112, second paragraph, as well as to include the features of canceled base claim 7.

As such, it is respectfully submitted that newly added independent claim 17 and its dependent claims 18 – 24 are allowable.

Independent Claim 25 and Dependent Claim 26:

Claims 25 and 26 correspond to canceled claim 8, which are rewritten to overcome the rejections under 35 U.S.C. 112 and 35 U.S.C. 103(a), and include to subject matter shown in FIGS. 7 and 8 of the present invention regarding the features that the antenna-ground plane is

formed to extend up to a region in which the antenna-ground plane has no longer any effects for antenna functions, and a line conductor is provided on the antenna-ground plane in such region.

In addition, claim 26 has been rewritten according to Examiner's direction in Page 2 of Office Action. More specifically, claim 26 calls for structure as providing a line conductor on the antenna-ground plane which is effective for improving the integration density of a high-frequency semiconductor device.

It is respectfully submitted that neither of the applied references of Fukuura and Shiga disclose or suggest these features.

Independent Claim 32:

Independent Claim 32 corresponds to the structure shown in FIGS. 5 and 6 of the present application, in which both an antenna-ground plane and a line conductor, which form a high-frequency transmission line together with the ground plate, are formed together on a common surface of an interlayer insulation film. This structure increases the flexibility in the layout design of line conductor and is effective for improving the integration density of a high-frequency semiconductor device. The cited references Fukuura and Shiga do not disclose nor suggest such structure.

In view of the aforementioned amendments and accompanying remarks, Applicants submit that that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

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